MICROCHIP

Semiconductor Device Type:	SAC	VQFN-68-8x8x1mm-MatteSn			
Basic Substance	**CAS Number**	**"Contained In" Sub-Component**	**% Total Weight**	**mg/part**	**ppm**
Silicon	7440-21-3	Die	1.22	1.85	12187
Copper	7440-50-8	Lead Frame	45.64	69.28	456403
Iron	7439-89-6	Lead Frame	1.08	1.65	10844
Zinc	7440-66-6	Lead Frame	0.09	0.14	943
Silver	7440-24-4	Lead Frame	0.33	0.50	3300
Silver	7440-22-4	Epoxy	0.18	0.28	1845
Resin Proprietary	Trade Secret	Epoxy	0.01	0.01	92
exo-1,7,7-trimethylbicyclo（2.2.1）hept-2-ylmethacrylate	7534-94-3	Epoxy	0.03	0.05	346
s (2,3-epoxypropyl)phenol;4-allyl-6-[3-[6-[3-[6-[3-(4-allyl-2,6-bis(2,3epoxyp	Trade Secret	Epoxy	0.00	0.00	12
Substitufed silane Proprietary	Trade Secret	Epoxy	0.00	0.00	12
Copper	7440-50-8	Wire	0.32	0.48	3162
Palladium	7440-05-3	Wire	0.01	0.02	99
Epoxy Resin	Trade Secret	Mold Compound	1.02	1.55	10186
Phenol Resin	Trade Secret	Mold Compound	1.02	1.55	10186
Silica(Amorphous) A	60676-86-0	Mold Compound	40.74	61.85	407444
Silica(Amorphous) B	7631-86-9	Mold Compound	7.64	11.60	76396
Carbon Black	1333-86-4	Mold Compound	0.51	0.77	5093
Tin	7440-31-5	Lead Finish Plating	0.14	0.22	1449
		TOTALS:	**100.00**	**151.80**	**1,000,000**

151.80 mg Total Mass

Package Homogeneous Materials

1.85	**(mg) Total**	**Die**	**% of Total Weight**	**1.22**
	Silicon	7440-21-3	100.00	
		Total	**100.00**	

71.57	**(mg) Total**	**Lead Frame**	**% of Total Weight**	**47.15**
	Copper	7440-50-8	96.80	
	Iron	7439-89-6	2.30	
	Zinc	7440-66-6	0.20	
	Silver	7440-24-4	0.70	
		Total	**100.00**	

0.35	**(mg) Total**	**Epoxy**	**% of Total Weight**	**0.23**
	Silver	7440-22-4	80.00	
	Resin Proprietary	Trade Secret	4.00	
	exo-1,7,7-trimethylbicyclo（2.2.1）hept-2-ylmethacrylate	7534-94-3	15.00	
	A mixture of: 4-allyl-2,6-bis (2,3-epoxypropyl)phenol;4-allyl-6-[3-[6-[3-[6-[3-(4-allyl-2,6-bis(2,3epoxypropyl)phenoxy)-2-hydroxyp	Trade Secret	0.50	
	Substitufed silane Proprietary	Trade Secret	0.50	
		Total	**100.00**	

0.50	**(mg) Total**	**Wire**	**% of Total Weight**	**0.33**
	Copper	7440-50-8	96.97	
	Palladium	7440-05-3	3.03	
		Total	**100.00**	

77.31	**(mg) Total**	**Mold Compound**	**% of Total Weight**	**50.93**
	Epoxy Resin	Trade Secret	2.00	
	Phenol Resin	Trade Secret	2.00	
	Silica(Amorphous) A	60676-86-0	80.00	
	Silica(Amorphous) B	7631-86-9	15.00	
	Carbon Black	1333-86-4	1.00	
		Total	**100.00**	

0.22	**(mg) Total**	**Lead Finish Plating**	**% of Total Weight**	**0.14**
	Tin	7440-31-5	100.00	
151.80		**Total**	**100.00**	100.00

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.

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